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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	43
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	2.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21346cnfp-30

1.2 Product List

Table 1.3 lists Product List for R8C/34C Group, and Figure 1.1 shows a Part Number, Memory Size, and Package of R8C/34C Group.

Table 1.3 Product List for R8C/34C Group

Current of Aug 2010

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks
	Program ROM	Data flash			
R5F21344CNFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0048KB-A	N version
R5F21345CNFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0048KB-A	
R5F21346CNFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0048KB-A	
R5F21344CDFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0048KB-A	D version
R5F21345CDFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0048KB-A	
R5F21346CDFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0048KB-A	

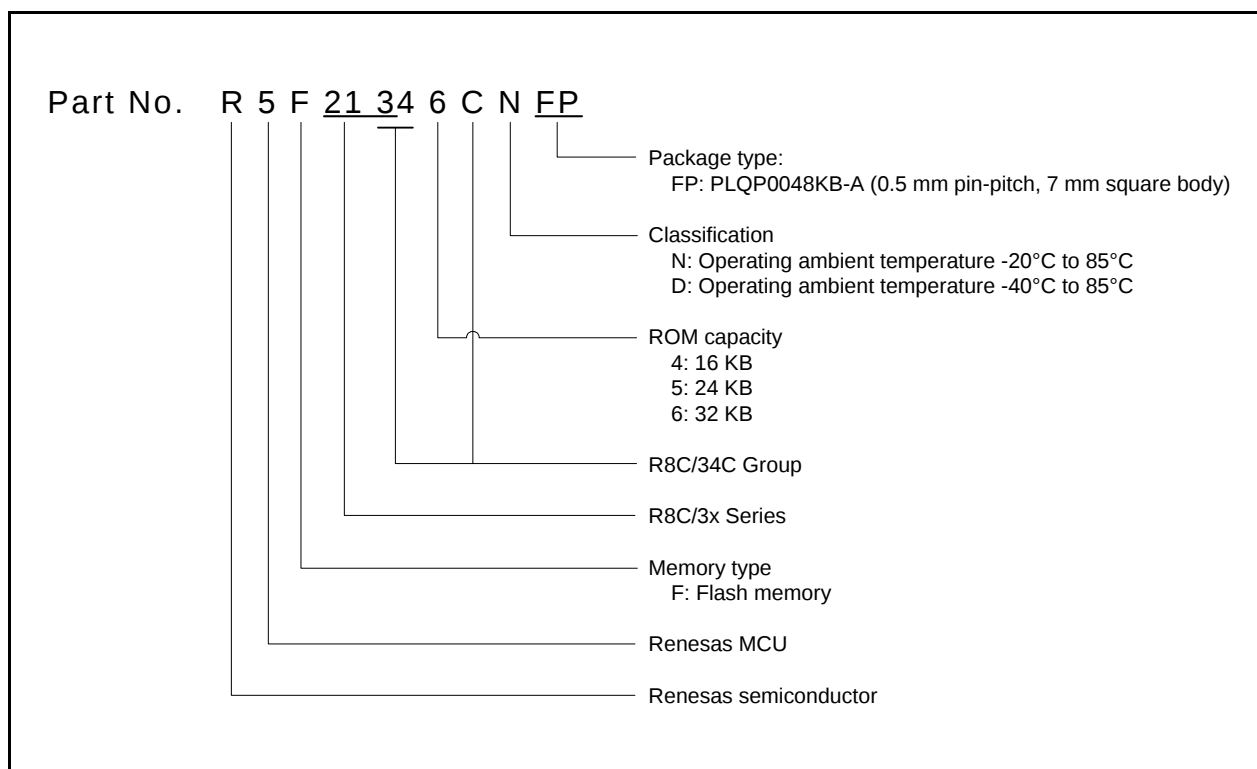


Figure 1.1 Part Number, Memory Size, and Package of R8C/34C Group

1.3 Block Diagram

Figure 1.2 shows a Block Diagram.

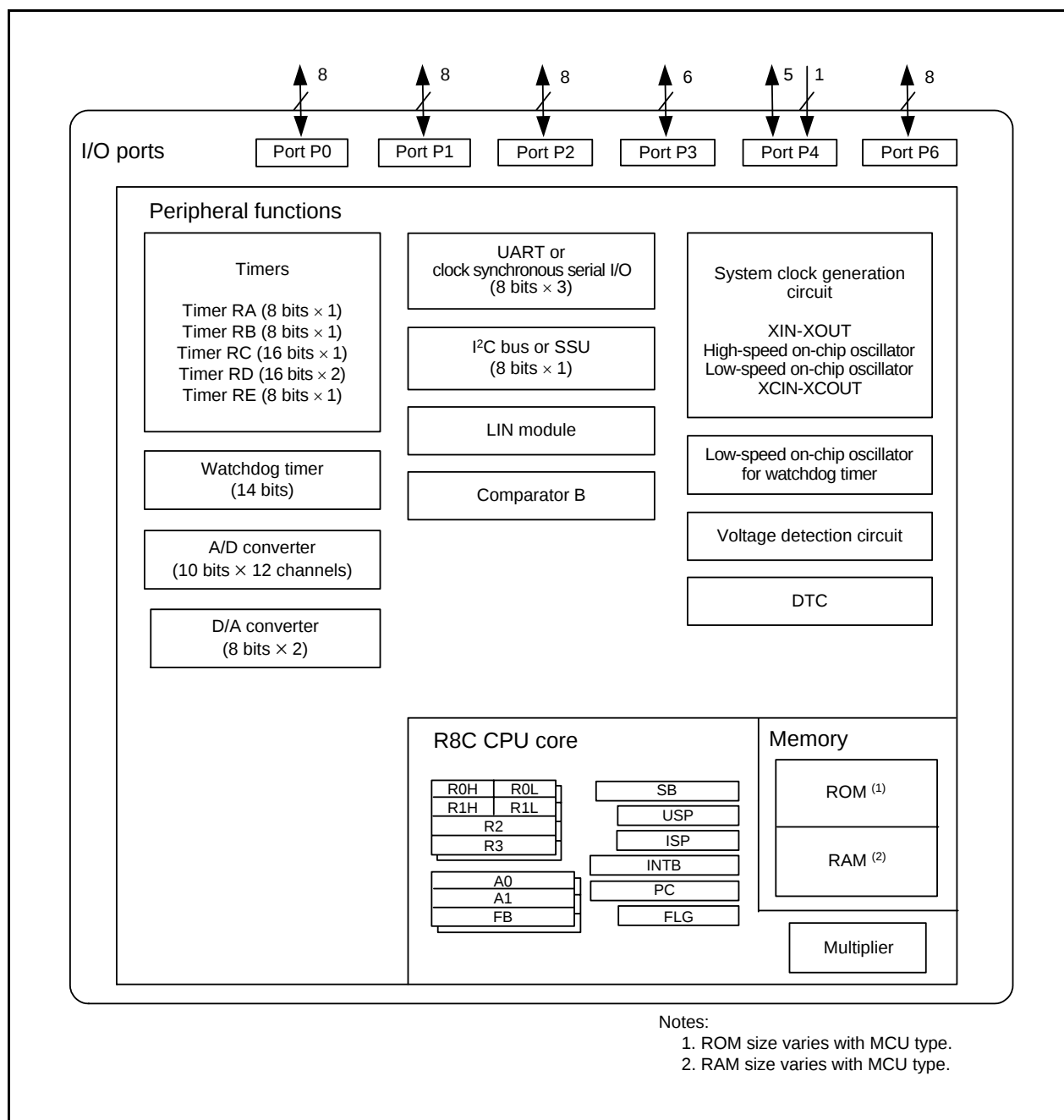


Figure 1.2 Block Diagram

1.4 Pin Assignment

Figure 1.3 shows the Pin Assignment (Top View). Tables 1.4 and 1.5 outline the Pin Name Information by Pin Number.

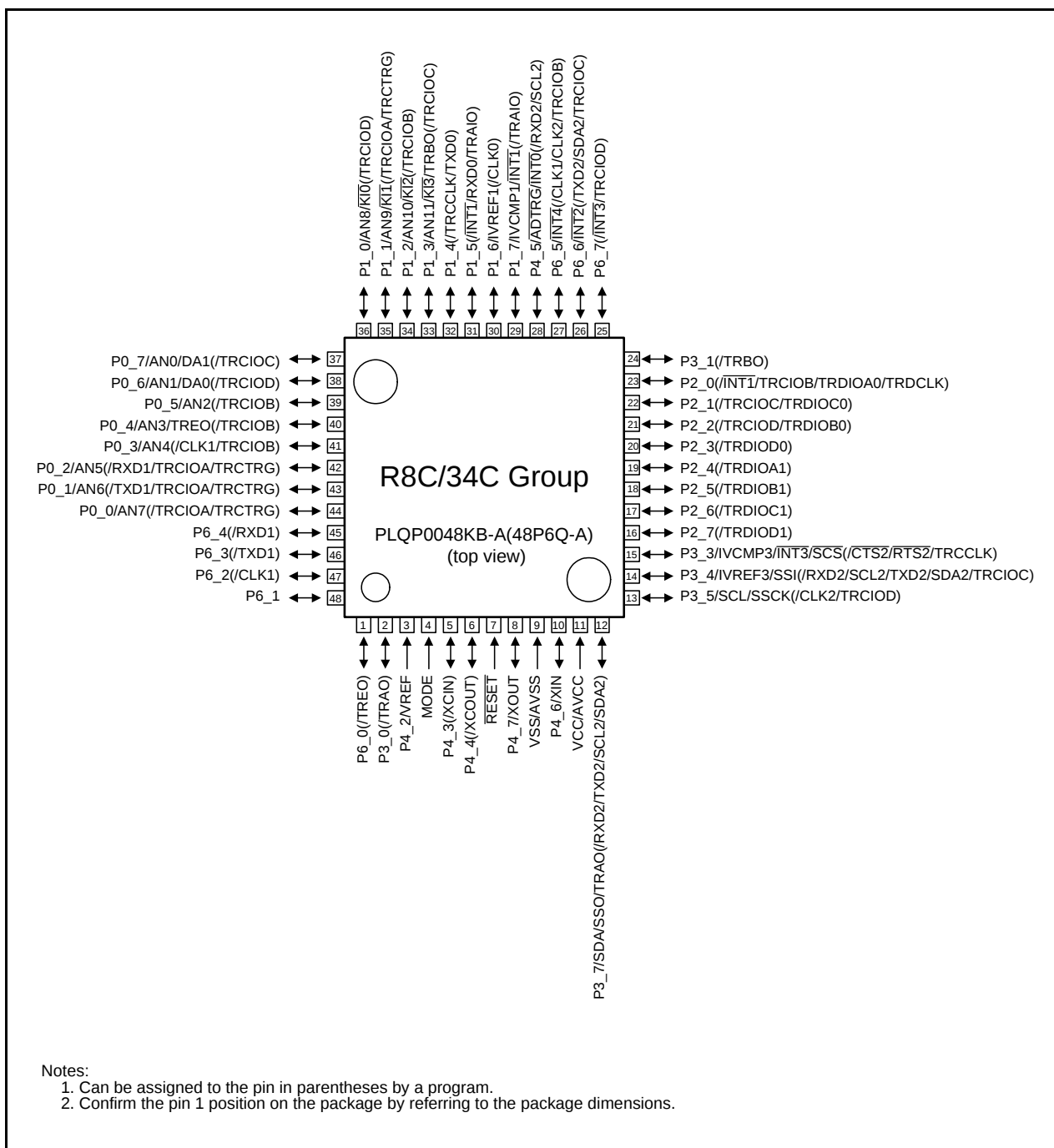


Figure 1.3 Pin Assignment (Top View)

Table 1.4 Pin Name Information by Pin Number (1)

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I ² C bus	A/D Converter, D/A Converter, Comparator B
1		P6_0		(TREO)				
2		P3_0		(TRAO)				
3		P4_2						VREF
4	MODE							
5	(XCIN)	P4_3						
6	(XCOUT)	P4_4						
7	RESET							
8	XOUT	P4_7						
9	VSS/AVSS							
10	XIN	P4_6						
11	VCC/AVCC							
12		P3_7		TRAO	(RXD2/SCL2/ TXD2/SDA2)	SSO	SDA	
13		P3_5		(TRCIOD)	(CLK2)	SSCK	SCL	
14		P3_4		(TRCIOC)	(RXD2/SCL2/ TXD2/SDA2)	SSI		IVREF3
15		P3_3	$\overline{\text{INT3}}$	(TRCCLK)	(CTS2/RTS2)	$\overline{\text{SCS}}$		IVCMP3
16		P2_7		(TRDIOD1)				
17		P2_6		(TRDIOC1)				
18		P2_5		(TRDIOB1)				
19		P2_4		(TRDIOA1)				
20		P2_3		(TRDIOD0)				
21		P2_2		(TRCIOD/ TRDIOB0)				
22		P2_1		(TRCIOC/ TRDIOC0)				
23		P2_0	($\overline{\text{INT1}}$)	(TRCIOB/ TRDIOA0/ TRDCLK)				
24		P3_1		(TRBO)				
25		P6_7	($\overline{\text{INT3}}$)	(TRCIOD)				
26		P6_6	$\overline{\text{INT2}}$	(TRCIOC)	(TXD2/SDA2)			
27		P6_5	$\overline{\text{INT4}}$	(TRCIOB)	(CLK1/CLK2)			
28		P4_5	$\overline{\text{INT0}}$		(RXD2/SCL2)			$\overline{\text{ADTRG}}$
29		P1_7	$\overline{\text{INT1}}$	(TRAIO)				IVCMP1
30		P1_6			(CLK0)			IVREF1
31		P1_5	($\overline{\text{INT1}}$)	(TRAIO)	(RXD0)			
32		P1_4		(TRCCLK)	(TXD0)			
33		P1_3	$\overline{\text{KI3}}$	TRBO/ (TRCIOC)				AN11
34		P1_2	$\overline{\text{KI2}}$	(TRCIOB)				AN10
35		P1_1	$\overline{\text{KI1}}$	(TRCIOA/ TRCTR)				AN9

Note:

1. Can be assigned to the pin in parentheses by a program.

3. Memory

3.1 R8C/34C Group

Figure 3.1 is a Memory Map of R8C/34C Group. The R8C/34C Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 32-Kbyte internal ROM area is allocated addresses 08000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.

The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM area is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.

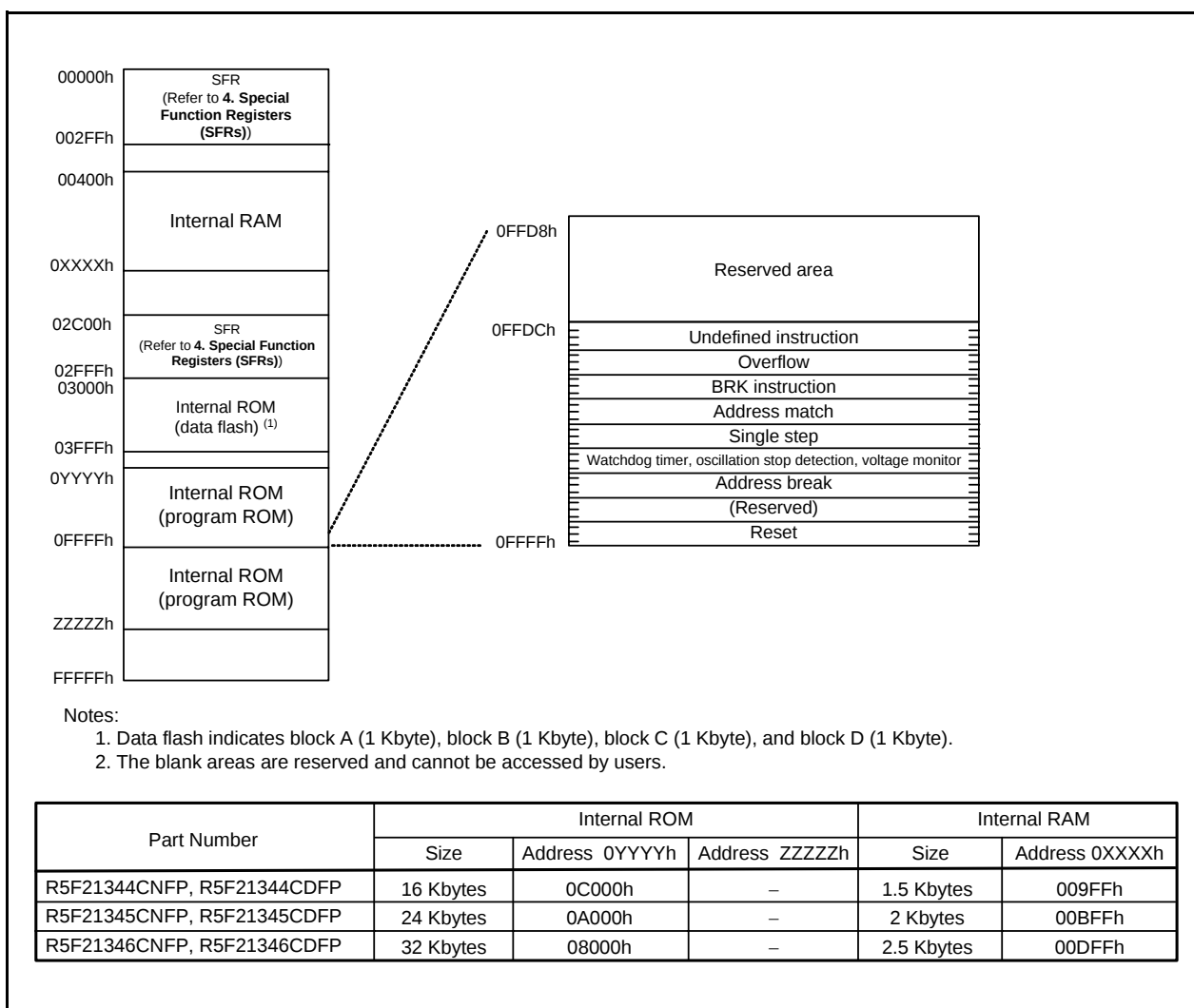


Figure 3.1 Memory Map of R8C/34C Group

Table 4.7 SFR Information (7) ⁽¹⁾

Address	Register	Symbol	After Reset
0180h	Timer RA Pin Select Register	TRASR	00h
0181h	Timer RB/RC Pin Select Register	TRBRCSR	00h
0182h	Timer RC Pin Select Register 0	TRCPSR0	00h
0183h	Timer RC Pin Select Register 1	TRCPSR1	00h
0184h	Timer RD Pin Select Register 0	TRDPSR0	00h
0185h	Timer RD Pin Select Register 1	TRDPSR1	00h
0186h	Timer Pin Select Register	TIMSR	00h
0187h			
0188h	UART0 Pin Select Register	U0SR	00h
0189h	UART1 Pin Select Register	U1SR	00h
018Ah	UART2 Pin Select Register 0	U2SR0	00h
018Bh	UART2 Pin Select Register 1	U2SR1	00h
018Ch	SSU/IIC Pin Select Register	SSUICSR	00h
018Dh			
018Eh	INT Interrupt Input Pin Select Register	INTSR	00h
018Fh	I/O Function Pin Select Register	PINSR	00h
0190h			
0191h			
0192h			
0193h	SS Bit Counter Register	SSBR	11111000b
0194h	SS Transmit Data Register L / IIC bus Transmit Data Register ⁽²⁾	SSTDR / ICDRT	FFh
0195h	SS Transmit Data Register H ⁽²⁾	SSTDRH	FFh
0196h	SS Receive Data Register L / IIC bus Receive Data Register ⁽²⁾	SSRDR / ICDRR	FFh
0197h	SS Receive Data Register H ⁽²⁾	SSRDRH	FFh
0198h	SS Control Register H / IIC bus Control Register 1 ⁽²⁾	SSCRH / ICCR1	00h
0199h	SS Control Register L / IIC bus Control Register 2 ⁽²⁾	SSCRL / ICCR2	01111101b
019Ah	SS Mode Register / IIC bus Mode Register ⁽²⁾	SSMR / ICMR	00010000b / 00011000b
019Bh	SS Enable Register / IIC bus Interrupt Enable Register ⁽²⁾	SSER / ICIER	00h
019Ch	SS Status Register / IIC bus Status Register ⁽²⁾	SSSR / ICSR	00h / 0000X000b
019Dh	SS Mode Register 2 / Slave Address Register ⁽²⁾	SSMR2 / SAR	00h
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h	Flash Memory Status Register	FST	10000X00b
01B3h			
01B4h	Flash Memory Control Register 0	FMR0	00h
01B5h	Flash Memory Control Register 1	FMR1	00h
01B6h	Flash Memory Control Register 2	FMR2	00h
01B7h			
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			

X: Undefined

Notes:

1. The blank areas are reserved and cannot be accessed by users.
2. Selectable by the IICSEL bit in the SSUICSR register.

Table 4.12 SFR Information (12) ⁽¹⁾

Address	Register	Symbol	After Reset
2CF0h	DTC Control Data 22	DTCD22	XXh
2CF1h			XXh
2CF2h			XXh
2CF3h			XXh
2CF4h			XXh
2CF5h			XXh
2CF6h			XXh
2CF7h			XXh
2CF8h	DTC Control Data 23	DTCD23	XXh
2CF9h			XXh
2CFAh			XXh
2CFBh			XXh
2CFCh			XXh
2CFDh			XXh
2CFEh			XXh
2CFFh			XXh
2D00h			
:			
2FFFh			

X: Undefined

Note:

- The blank areas are reserved and cannot be accessed by users.

Table 4.13 ID Code Areas and Option Function Select Area

Address	Area Name	Symbol	After Reset
:			
FFDBh	Option Function Select Register 2	OFS2	(Note 1)
:			
FFDFh	ID1		(Note 2)
:			
FFE3h	ID2		(Note 2)
:			
FFEBh	ID3		(Note 2)
:			
FFEFh	ID4		(Note 2)
:			
FFF3h	ID5		(Note 2)
:			
FFF7h	ID6		(Note 2)
:			
FFFBh	ID7		(Note 2)
:			
FFFFh	Option Function Select Register	OFS	(Note 1)

Notes:

- The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not write additions to the option function select area. If the block including the option function select area is erased, the option function select area is set to FFh.
When blank products are shipped, the option function select area is set to FFh. It is set to the written value after written by the user.
When factory-programming products are shipped, the value of the option function select area is the value programmed by the user.
- The ID code areas are allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not write additions to the ID code areas. If the block including the ID code areas is erased, the ID code areas are set to FFh.
When blank products are shipped, the ID code areas are set to FFh. They are set to the written value after written by the user.
When factory-programming products are shipped, the value of the ID code areas is the value programmed by the user.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V _{CC} /AV _{CC}	Supply voltage		−0.3 to 6.5	V
V _I	Input voltage		−0.3 to V _{CC} + 0.3	V
V _O	Output voltage		−0.3 to V _{CC} + 0.3	V
P _d	Power dissipation	−40°C ≤ T _{opr} ≤ 85°C	500	mW
T _{opr}	Operating ambient temperature		−20 to 85 (N version) / −40 to 85 (D version)	°C
T _{stg}	Storage temperature		−65 to 150	°C

Table 5.2 Recommended Operating Conditions

Symbol	Parameter				Conditions	Standard			Unit
						Min.	Typ.	Max.	
V _{CC} /AV _{CC}	Supply voltage					1.8	–	5.5	V
V _{SS} /AV _{SS}	Supply voltage					–	0	–	V
V _{IH}	Input “H” voltage	Other than CMOS input				0.8 V _{CC}	–	V _{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.5 V _{CC}	–	V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0.55 V _{CC}	–	V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0.65 V _{CC}	–	V _{CC}	V
			Input level selection : 0.5 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.65 V _{CC}	–	V _{CC}	V	
				2.7 V ≤ V _{CC} < 4.0 V	0.7 V _{CC}	–	V _{CC}	V	
				1.8 V ≤ V _{CC} < 2.7 V	0.8 V _{CC}	–	V _{CC}	V	
			Input level selection : 0.7 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0.85 V _{CC}	–	V _{CC}	V	
				2.7 V ≤ V _{CC} < 4.0 V	0.85 V _{CC}	–	V _{CC}	V	
				1.8 V ≤ V _{CC} < 2.7 V	0.85 V _{CC}	–	V _{CC}	V	
	External clock input (XOUT)				1.2	–	V _{CC}	V	
V _{IL}	Input “L” voltage	Other than CMOS input				0	–	0.2 V _{CC}	V
		CMOS input	Input level switching function (I/O port)	Input level selection : 0.35 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	–	0.2 V _{CC}	V
					2.7 V ≤ V _{CC} < 4.0 V	0	–	0.2 V _{CC}	V
					1.8 V ≤ V _{CC} < 2.7 V	0	–	0.2 V _{CC}	V
			Input level selection : 0.5 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	–	0.4 V _{CC}	V	
				2.7 V ≤ V _{CC} < 4.0 V	0	–	0.3 V _{CC}	V	
				1.8 V ≤ V _{CC} < 2.7 V	0	–	0.2 V _{CC}	V	
			Input level selection : 0.7 V _{CC}	4.0 V ≤ V _{CC} ≤ 5.5 V	0	–	0.55 V _{CC}	V	
				2.7 V ≤ V _{CC} < 4.0 V	0	–	0.45 V _{CC}	V	
				1.8 V ≤ V _{CC} < 2.7 V	0	–	0.35 V _{CC}	V	
	External clock input (XOUT)				0	–	0.4	V	
I _{OH} (sum)	Peak sum output “H” current	Sum of all pins I _{OH} (peak)				–	–	–160	mA
I _{OH} (sum)	Average sum output “H” current	Sum of all pins I _{OH} (avg)				–	–	–80	mA
I _{OH} (peak)	Peak output “H” current	Drive capacity Low				–	–	–10	mA
		Drive capacity High				–	–	–40	mA
I _{OH} (avg)	Average output “H” current	Drive capacity Low				–	–	–5	mA
		Drive capacity High				–	–	–20	mA
I _{OL} (sum)	Peak sum output “L” current	Sum of all pins I _{OL} (peak)				–	–	160	mA
I _{OL} (sum)	Average sum output “L” current	Sum of all pins I _{OL} (avg)				–	–	80	mA
I _{OL} (peak)	Peak output “L” current	Drive capacity Low				–	–	10	mA
		Drive capacity High				–	–	40	mA
I _{OL} (avg)	Average output “L” current	Drive capacity Low				–	–	5	mA
		Drive capacity High				–	–	20	mA
f _(XIN)	XIN clock input oscillation frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	–	–	5	MHz
f _(XCIN)	XCIN clock input oscillation frequency				1.8 V ≤ V _{CC} ≤ 5.5 V	–	32.768	50	kHz
f _{OCO40M}	When used as the count source for timer RC or timer RD ⁽³⁾				2.7 V ≤ V _{CC} ≤ 5.5 V	32	–	40	MHz
f _{OCO-F}	f _{OCO-F} frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	–	–	5	MHz
–	System clock frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	–	–	5	MHz
f _(BCLK)	CPU clock frequency				2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
					1.8 V ≤ V _{CC} < 2.7 V	–	–	5	MHz

Notes:

1. V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. The average output current indicates the average value of current measured during 100 ms.
3. f_{OCO40M} can be used as the count source for timer RC or timer RD in the range of V_{CC} = 2.7 V to 5.5V.

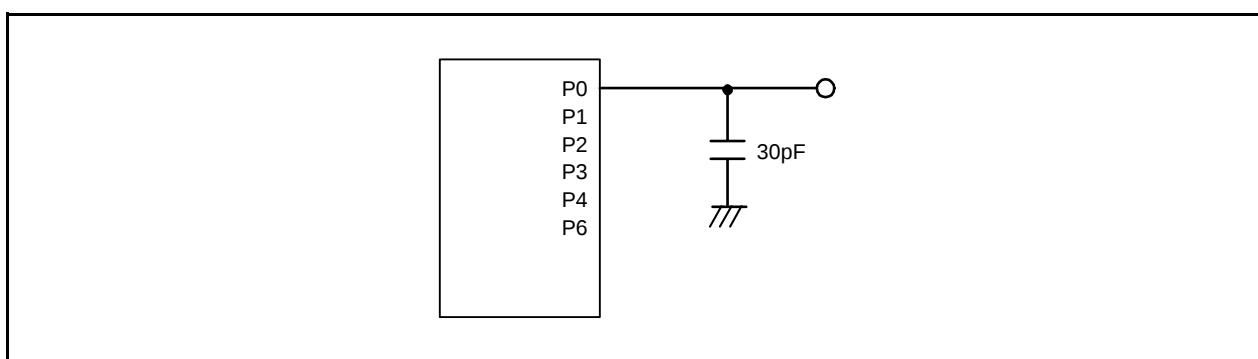


Figure 5.1 Ports P0 to P4, P6 Timing Measurement Circuit

Table 5.12 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
–	High-speed on-chip oscillator frequency after reset	$V_{CC} = 1.8\text{V to } 5.5\text{ V}$ $-20^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	38.4	40	41.6	MHz
		$V_{CC} = 1.8\text{V to } 5.5\text{ V}$ $-40^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	38.0	40	42.0	MHz
	High-speed on-chip oscillator frequency when the FRA4 register correction value is written into the FRA1 register and the FRA5 register correction value into the FRA3 register ⁽²⁾	$V_{CC} = 1.8\text{V to } 5.5\text{ V}$ $-20^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	35.389	36.864	38.338	MHz
		$V_{CC} = 1.8\text{V to } 5.5\text{ V}$ $-40^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	35.020	36.864	38.707	MHz
	High-speed on-chip oscillator frequency when the FRA6 register correction value is written into the FRA1 register and the FRA7 register correction value into the FRA3 register	$V_{CC} = 1.8\text{V to } 5.5\text{ V}$ $-20^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	30.72	32	33.28	MHz
		$V_{CC} = 1.8\text{V to } 5.5\text{ V}$ $-40^{\circ}\text{C} \leq T_{opr} \leq 85^{\circ}\text{C}$	30.40	32	33.60	MHz
–	Oscillation stability time	$V_{CC} = 5.0\text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	0.5	3	ms
–	Self power consumption at oscillation	$V_{CC} = 5.0\text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	400	–	μA

Notes:

1. $V_{CC} = 1.8$ to 5.5 V , $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.13 Low-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		60	125	250	kHz
–	Oscillation stability time	$V_{CC} = 5.0\text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	30	100	μs
–	Self power consumption at oscillation	$V_{CC} = 5.0\text{ V}$, $T_{opr} = 25^{\circ}\text{C}$	–	2	–	μA

Note:

1. $V_{CC} = 1.8$ to 5.5 V , $T_{opr} = -20$ to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.

Table 5.14 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _d (P-R)	Time for internal power supply stabilization during power-on ⁽²⁾		–	–	2,000	μs

Notes:

1. The measurement condition is $V_{CC} = 1.8$ to 5.5 V and $T_{opr} = 25^{\circ}\text{C}$.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.

Table 5.15 Timing Requirements of Synchronous Serial Communication Unit (SSU) (1)

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	–	–	tcyc (2)
tHI	SSCK clock "H" width			0.4	–	0.6	tsucyc
tLO	SSCK clock "L" width			0.4	–	0.6	tsucyc
tRISE	SSCK clock rising time	Master		–	–	1	tcyc (2)
		Slave		–	–	1	μs
tFALL	SSCK clock falling time	Master		–	–	1	tcyc (2)
		Slave		–	–	1	μs
tsu	SSO, SSI data input setup time			100	–	–	ns
tH	SSO, SSI data input hold time			1	–	–	tcyc (2)
tLEAD	SCS setup time	Slave		1tcyc + 50	–	–	ns
tLAG	SCS hold time	Slave		1tcyc + 50	–	–	ns
tOD	SSO, SSI data output delay time			–	–	1	tcyc (2)
tsa	SSI slave access time		2.7 V ≤ Vcc ≤ 5.5 V	–	–	1.5tcyc + 100	ns
			1.8 V ≤ Vcc < 2.7 V	–	–	1.5tcyc + 200	ns
tor	SSI slave out open time		2.7 V ≤ Vcc ≤ 5.5 V	–	–	1.5tcyc + 100	ns
			1.8 V ≤ Vcc < 2.7 V	–	–	1.5tcyc + 200	ns

Notes:

1. Vcc = 1.8 to 5.5 V, Vss = 0 V and Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. 1tcyc = 1/f1(s)

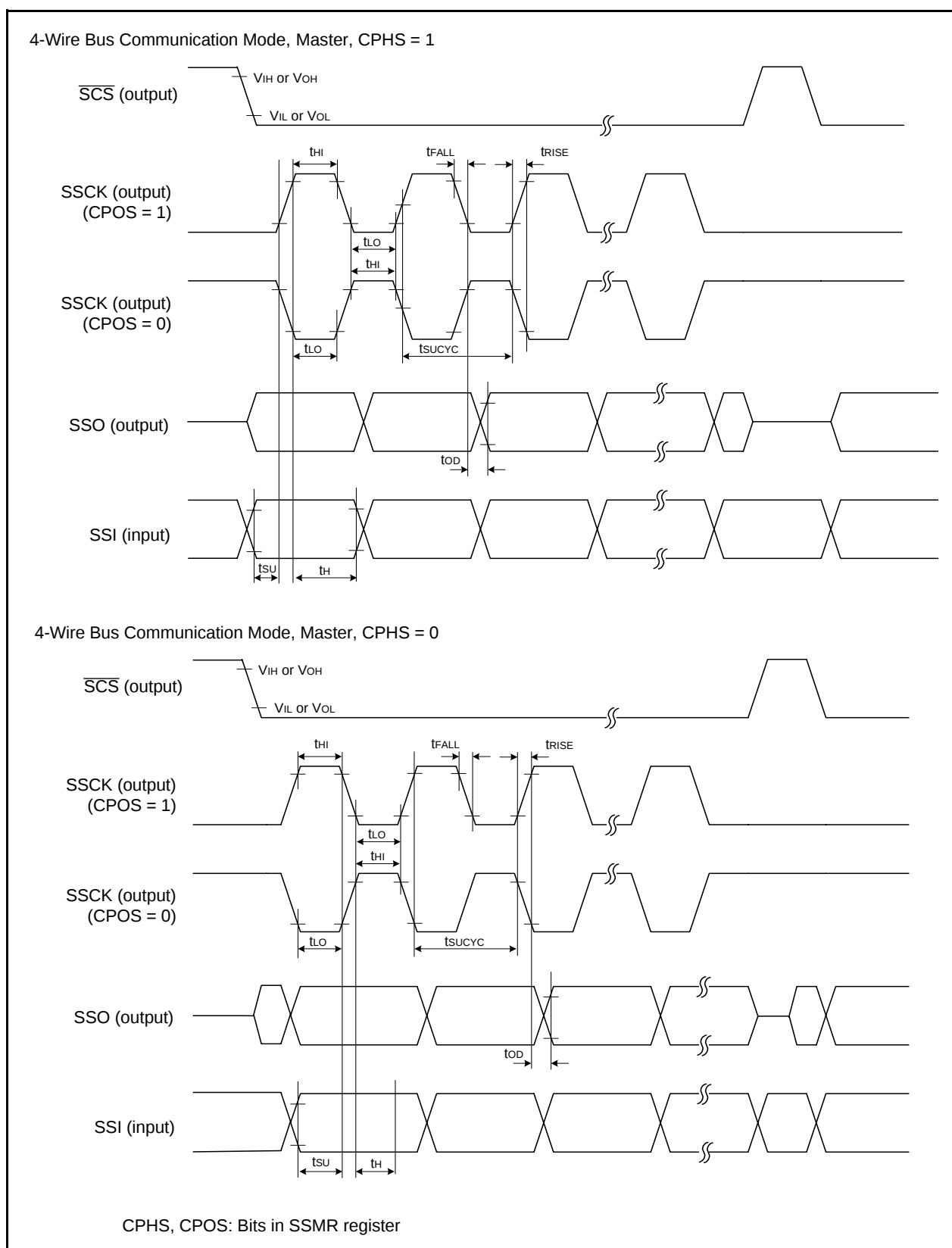


Figure 5.4 I/O Timing of Synchronous Serial Communication Unit (SSU) (Master)

Table 5.16 Timing Requirements of I²C bus Interface (1)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{SCL}	SCL input cycle time		12t _{cy} + 600 (2)	–	–	ns
t _{SCLH}	SCL input “H” width		3t _{cy} + 300 (2)	–	–	ns
t _{SCLL}	SCL input “L” width		5t _{cy} + 500 (2)	–	–	ns
t _{sf}	SCL, SDA input fall time		–	–	300	ns
t _{SP}	SCL, SDA input spike pulse rejection time		–	–	1t _{cy} (2)	ns
t _{BUF}	SDA input bus-free time		5t _{cy} (2)	–	–	ns
t _{STAH}	Start condition input hold time		3t _{cy} (2)	–	–	ns
t _{STAS}	Retransmit start condition input setup time		3t _{cy} (2)	–	–	ns
t _{STOP}	Stop condition input setup time		3t _{cy} (2)	–	–	ns
t _{SDAS}	Data input setup time		1t _{cy} + 40 (2)	–	–	ns
t _{SDAH}	Data input hold time		10	–	–	ns

Notes:

1. V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. 1t_{cy} = 1/f₁(s)

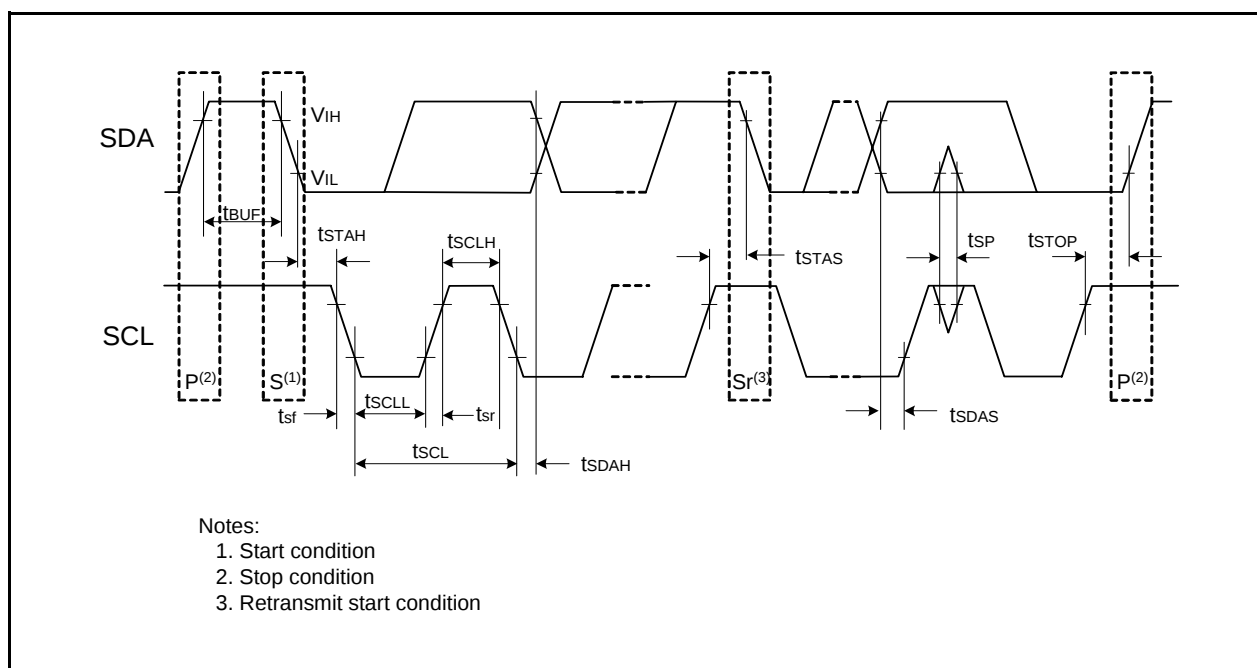
**Figure 5.7** I/O Timing of I²C bus Interface

Table 5.17 Electrical Characteristics (1) [$4.2\text{ V} \leq V_{CC} \leq 5.5\text{ V}$]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Other than XOUT	Drive capacity High V _{CC} = 5V	I _{OH} = -20 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity Low V _{CC} = 5V	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
		XOUT	V _{CC} = 5V	I _{OH} = -200 μ A	1.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Other than XOUT	Drive capacity High V _{CC} = 5V	I _{OL} = 20 mA	—	—	2.0	V
			Drive capacity Low V _{CC} = 5V	I _{OL} = 5 mA	—	—	2.0	V
		XOUT	V _{CC} = 5V	I _{OL} = 200 μ A	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.1	1.2	—	V
		RESET			0.1	1.2	—	V
I _{IH}	Input "H" current		V _I = 5 V, V _{CC} = 5.0 V		—	—	5.0	μ A
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 5.0 V		—	—	-5.0	μ A
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 5.0 V		25	50	100	k Ω
R _{FXIN}	Feedback resistance	XIN			—	0.3	—	M Ω
R _{FXCIN}	Feedback resistance	XCIN			—	8	—	M Ω
V _{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:

1. $4.2\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.18 Electrical Characteristics (2) [$3.3\text{ V} \leq V_{CC} \leq 5.5\text{ V}$]
($T_{opr} = -20\text{ to }85^{\circ}\text{C}$ (N version) / $-40\text{ to }85^{\circ}\text{C}$ (D version), unless otherwise specified.)

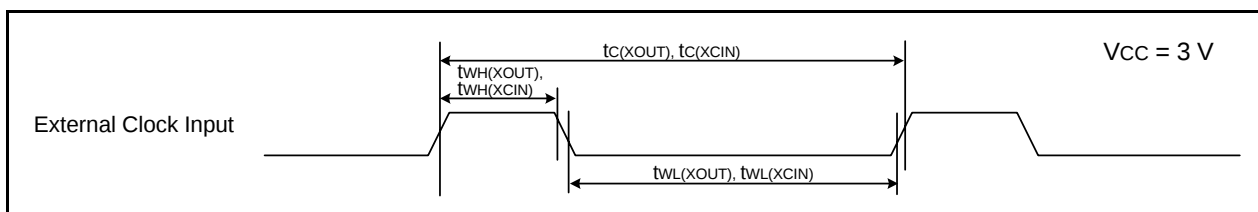
Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are Vss	High-speed clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	—	6.5	15	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	—	5.3	12.5	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	—	3.6	—	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	3.0	—	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	2.2	—	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	1.5	—	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	—	7.0	15	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	3.0	—	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 4 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-16 MSTIIC = MSTTRD = MSTTRC = 1	—	1	—	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	—	90	400	μA
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division FMR27 = 1, VCA20 = 0	—	85	400	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz No division Program operation on RAM Flash memory off, FMSTP = 1, VCA20 = 0	—	47	—	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	—	15	100	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	—	4	90	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (peripheral clock off) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	—	3.5	—	μA
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	—	2.0	5.0	μA
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	—	5.0	—	μA

Table 5.24 Electrical Characteristics (4) [$2.7\text{ V} \leq V_{CC} < 3.3\text{ V}$]
($T_{opr} = -20\text{ to }85^{\circ}\text{C}$ (N version) / $-40\text{ to }85^{\circ}\text{C}$ (D version), unless otherwise specified.)

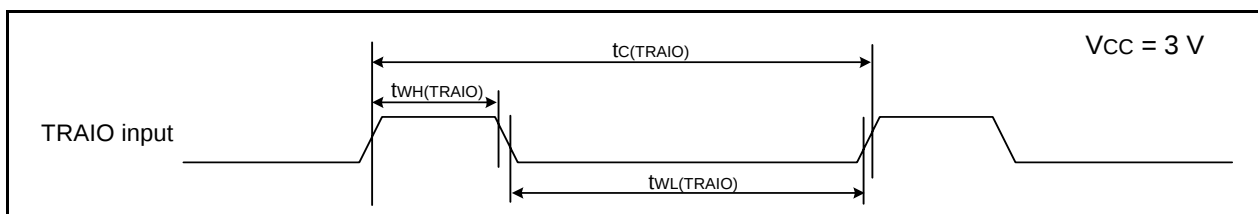
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
I _{CC}	Power supply current ($V_{CC} = 2.7\text{ to }3.3\text{ V}$) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode	—	3.5	10	mA
			—	1.5	7.5	mA
		High-speed on-chip oscillator mode	—	7.0	15	mA
			—	3.0	—	mA
			—	4.0	—	mA
			—	1.5	—	mA
			—	1	—	mA
		Low-speed on-chip oscillator mode	—	90	390	μA
		Low-speed clock mode	—	80	400	μA
		Wait mode	—	15	90	μA
		Stop mode	—	2.0	5.0	μA
			—	5.0	—	μA

Timing Requirements**(Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^{\circ}\text{C}$)****Table 5.25 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	50	–	ns
$t_{WH(XOUT)}$	XOUT input “H” width	24	–	ns
$t_{WL(XOUT)}$	XOUT input “L” width	24	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

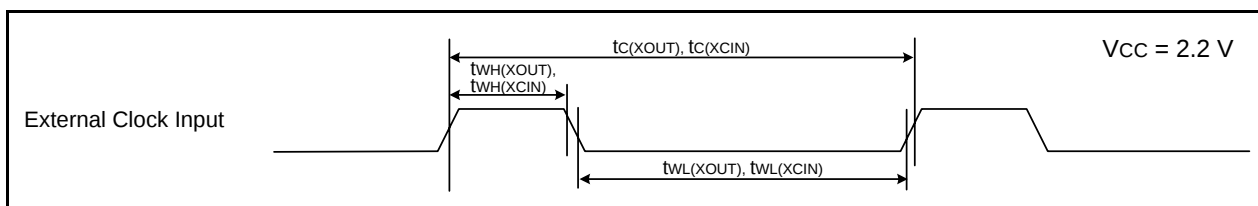
**Figure 5.12 External Clock Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.26 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	120	–	ns

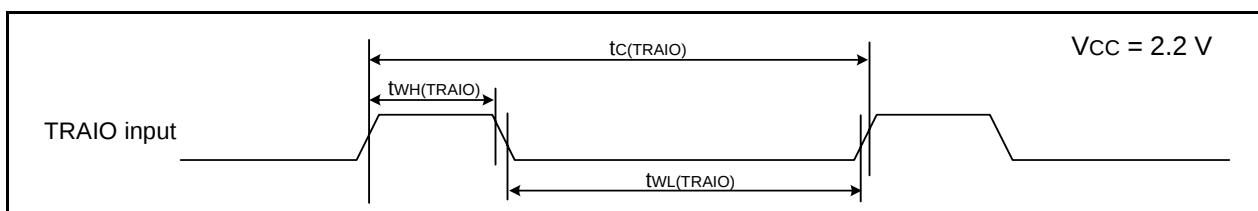
**Figure 5.13 TRAIO Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Timing Requirements**(Unless Otherwise Specified: $V_{CC} = 2.2\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^\circ\text{C}$)****Table 5.31 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	200	–	ns
$t_{WH(XOUT)}$	XOUT input “H” width	90	–	ns
$t_{WL(XOUT)}$	XOUT input “L” width	90	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.16 External Clock Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.32 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	500	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	200	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	200	–	ns

**Figure 5.17 TRAIO Input Timing Diagram when $V_{CC} = 2.2\text{ V}$**

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Electronics website.

